

RECEIVED  
CENTRAL FAX CENTER

JAN 24 2005

**PATENT**  
**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of Applicants:

Date: January 17, 2005

Bietsch, et al.

Group Art Unit: 1751

Serial No.: 10/081,860

Examiner: LynetteT Umez Eronini

Filed: February 22, 2002

Docket No.: CH920010003US1

For: *SELECTIVE ETCHING OF SUBSTRATES WITH CONTROL OF THE ETCH PROFILE*

Assistant Commissioner for Patents  
Post Office Box 1450  
Alexandria, VA 22313-1450

**IN THE CLAIMS:**

Cancel Claims 2 - 5 and 22 - 45 as drawn to a non-elected invention. Add Claims 46 and 47 to the invention under examination as these claims are sub-species of the claims upon which they depend.

In response to the Official Action dated January 6, 2005, please amend the above-identified application as set forth in the Appendix attached hereto.

**REMARKS**

Applicants acknowledge the requirement for restriction set forth in the Official Action. Applicants confirm election of Claims 1 - 21 drawn to an etching composition. It is submitted that the claims as amended in the instant response will place the claims in condition for allowance so that process claims 22 - 45 drawn to the method of selectively patterning a substrate could be easily amended and also placed in condition for allowance. Applicants reserve the right to file a divisional application on the cancelled method claims.

The misspelling found in Claim 17 has been corrected.